

SOT1199-1

plastic very thin fine-pitch ball grid array package; 24 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA24
Package type industry code	VFBGA24
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	- - -
Mounting method type	S (surface mount)
Issue date	16-2-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	0.75	-	0.85	1	mm
A ₂	package height	0.6	-	0.65	0.75	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

VFBGA24: plastic very thin fine-pitch ball grid array package; 24 balls; body 3 x 3 x 0.85 mm

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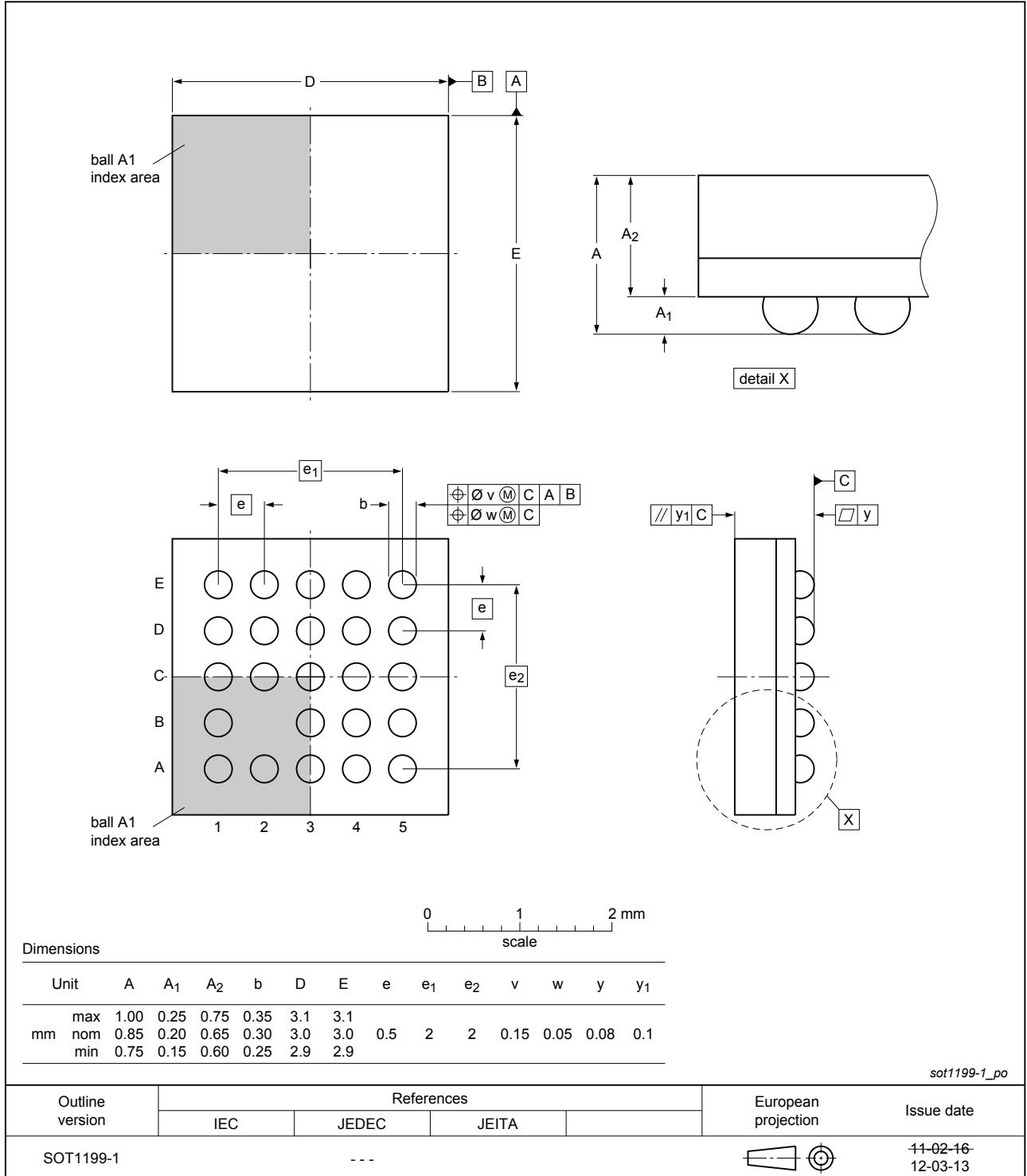


Fig. 1. Package outline VFBGA24 (SOT1199-1)

3. Legal information

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